

Final Product/Process Change Notification Document #:FPCN25572Z26 Issue Date:06 Mar 2024

Title of Change:	Update to FPCN25572Z - To include the reliability data for TSSOP-20 package parts for the Qualification of Vanguard Fab and Assembly related changes for Logic parts.	
Proposed Changed Material First Ship Date:	13 Sep 2024 or earlier if approved by customer	
Current Material Last Order Date:	20 Nov 2023 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.	
Current Material Last Delivery Date:	N/A The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory	
Product Category:	Active components – Integrated circuits	
Contact information:	Contact your local onsemi Sales Office or logic.fpcn@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Sample Availability Date:	31 Mar 2024	
PPAP Availability Date:	06 Apr 2024	
Additional Reliability Data:	Contact your local onsemi Sales Office or Changkit.Mok@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. The change will be implemented at 'Proposed Change Material First Ship Date' in compliance to J-STD-46 or ZVEI, or earlier upon customer approval, or per our signed agreements. onsemi will consider this proposed change and it's conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com.	
Change Category		
Category	Type of Change	
Test Flow	Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor	
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor, New wafer diameter	
Equipment	Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product	
Data Sheet	Change of datasheet parameters/electrical specification (min./max./typ. values) and/or AC/DC specification	
Process - Assembly	Move of all or part of assembly to a different location/site/subcontractor., Die attach material, Change of wire bonding	

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Description and Purpose:

With reference to FPCN25572Z, this FPCN presents the information solely for TSSOP-20 package and the pertinent reliability data.

	From	То
Fab Site	Tower Semiconductor	Vanguard International Semiconductor (VIS)
Wafer Size	150 mm	200 mm

Assembly and test changes as shown in the table below:

	From	Т)
Assembly Site	onsemi Carmona	onsemi Carmona	ATEC
Test Site	onsemi Carmona	onsemi Carmona	ATEC
Wire Type	0.8 mil Au, 0.8 mil Cu	1 mil PCC	1 mil PCC
Die Attach	CRM-1076WB	CRM-1076WB	QMI-519
Case Outline	948E	948E	948AQ

Reason / Motivation for Change:	Source/Supply/Capacity Changes Process/Materials Change		
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by onsemi in relation to the PCN, associated risks are verified and excluded. No anticipated impacts.		
Sites Affected:			
onsemi Sites		External Foundry/Subcon Sites	
onsemi Carmona, Philippines		ATEC - Automated Technology, Philippines	

	Vanguard International Semiconductor, Taiwan
Marking of Parts/ Traceability of Change:	Custom source on label will show TW instead of US/IL to indicate new die source from Vanguard. Changed material may be identified by plant code or lot code too.

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Reliability Data Summary:

> Refer to embedded excel RMS 089395 and 089401.

To view attachments:

- 1. Download pdf copy of the PCN to your computer
- 2. Open the downloaded pdf copy of the PCN
- 3. Click on the paper clip icon available on the menu provided in the left/bottom portion of the screen to reveal the Attachment field
- 4. Then click on the attached file.

Electrical Characteristics Summary:

	From	То
Datasheet	Current Revision	New Revision
Absolute Max Voltage Rating	7 V	6.5 V

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
NLVHCT244ADTR2G	MC74HCT244ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HC541ADTR2G	MC74HC541ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HC540ADTR2G	MC74HC540ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLVHCT541ADTR2G	MC74HCT541ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLVHCT374ADTR2G	MC74HCT374ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLVHCT245ADTR2G	MC74HCT245ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HCT574ADTRG	MC74HCT574ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HCT573ADTRG	MC74HCT573ADTRG-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HCT541ADTRG	MC74HCT541ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HC574ADTR2G	MC74HC574ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HC374ADTR2G	MC74HC374ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HC273ADTR2G	MC74HC273ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HC245ADTR2G	MC74HC245ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HC240ADTR2G	MC74HC240ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HC244ADTR2G	MC74HC244ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G
NLV74HC573ADTR2G	MC74HC573ADTR2G-Q	MC74HC244ADTR2G, NLV74HC244ADTR2G

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